Micross Components, Inc. ("Micross") headquartered in Orlando, Florida is pleased to announce the strategic acquisition of RTI International’s Microsystem Integration and Packaging ("MIP") Group, one of the premier wafer bumping and wafer level packaging research and fabrication facilities in the US, servicing commercial and government clients, situated in Research Triangle Park, North Carolina. The merger brings together MIP’s value-added semiconductor processing techniques, including wafer bumping, 2.5D/3D packaging and interconnects plus novel sensor and thermal management devices, with the global high-reliability electronics platform of Micross Components. This new division will be named Micross “Advanced Interconnect Technology (AIT)".

Innovative Next-Gen Packaging Solutions.
Micross Advanced Interconnect Technology offers advanced packaging and 3D integration solutions that enable higher-performance systems with decreased size, weight, and power (SWaP). We provide a wide variety of advanced interconnect technologies for realizing your next-generation electronic systems. These include flip-chip and wafer-level packaging, through-silicon vias (TSV), through-glass vias (TGV), high-density (fine-pitch) interconnects, and fabrication of Si or glass interposers. Micross AIT houses a state-of-the-art microfabrication facility that allows us to provide development, custom (flexible) prototyping and small-volume production services for our customers.

Providing Integration and Advanced Packaging Solutions across a Vast Array of Applications

 Microsystems are the building blocks of information technology and include components such as integrated circuits (ICs), photonic and optoelectronic ICs, and microelectromechanical systems (MEMS). Microsystem integration involves technologies for connecting the individual components into multifunctional electronic systems.

Micross AIT has been at the forefront of the development of such interconnect and packaging technologies for more than 25 years, making them accessible to external organizations for a wide variety of advanced and low-volume applications. We provide application-based solutions for government and industry clients, as well as collaborate with commercial and academic partners in technology areas such as high-performance sensor and actuator arrays, biomedical devices, and high-performance computing.

Our integration and packaging technologies include:

- 3D integration technology: TSV, TGV, Si interposers, 3D IC
- Advanced interconnect and packaging technologies: Solder bumping, Cu pillar, Cu-based microbumps, assembly
- Quilt packaging™ multi-project wafer offering: This technology enables the use of novel die geometries and the assembly of 3-D microsystems, while providing improved electric performance
- Microstructure fabrication and packaging: Monolithic integration, vacuum microelectronics, wafer-level vacuum packaging

More Information:

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ABOUT MICROSS

Micross is the leading one-source, one-solution provider of Bare Die & Wafers, Advanced Interconnect Technology, Custom Packaging & Assembly, Component Modification Services, Electrical & Environmental Testing and Hi-Rel Products to manufacturers and users of semiconductor devices. In business for more than 35 years, our comprehensive array of high-reliability capabilities serve the global Defense, Space, Medical, Industrial and Fabless Semiconductor markets. Micross possesses the sourcing, packaging, assembly, test and logistics expertise needed to support an application throughout its entire program cycle.

Micross AIT provides value-added semiconductor processing services for a diverse base of commercial clients, government agencies and academic institutions, supporting our clients through application-driven technology development programs, custom prototyping and small-volume production. We also partner with external organizations for joint proposals in a variety of government and defense programs. If you’re facing miniaturizing and integration challenges for your multifunctional systems, contact us to learn more about how we can help you obtain the best performance from your systems.